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RClamp3321P Ultra-Low Capacitance 1-Line, 3.3V ESD protection

PROTECTION PRODUCTS - RailClamp®

Description

The RClamp®3321P provides ESD protection for USB3.0, HDMI1.3/1.4, and other high-speed ports. It may be used to meet the ESD immunity requirements of IEC 61000-4-2. The RClamp3321P is designed to minimize both the ESD peak clamping and the TLP clamping. The dynamic resistance is minimized (0.47 Ohms typical) for optimum protection of sensitive circuits. Maximum capacitance is only 0.35pF. This allows the RClamp3321P to be used in applications operating in excess of 5GHz without signal attenuation. These devices are manufactured using Semtech's proprietary low voltage technology for superior characteritics at operating voltages up to 3.3 volts.

The RClamp3321P is in a 2-pin SLP1006P2 package. It measures $1.0 \times 0.6 \times 0.5$ mm. The leads are spaced at a pitch of 0.65mm and are finished with lead-free NiPdAu. Each device will protect one line operating at 3.3 volts. The combination of low peak ESD clamping, low dynamic resistance, and low capacitance makes this device suitable for applications such as USB 3.0, HDMI and V-By-One interfaces in portable devices.

Features

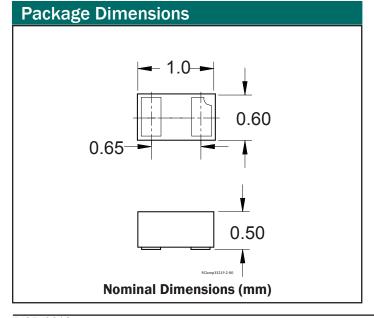
- ◆ Transient protection for data lines to IEC 61000-4-2 (ESD) ±17kV (air), ±12kV (contact) IEC 61000-4-4 (EFT) 40A (tp = 5/50ns) Cable Discharge Event (CDE)
- ◆ Ultra-small package (1.0 x 0.6 x 0.5mm)
- ◆ Protects one data or I/O line
- Low capacitance: 0.35pF
- Dynamic Resistance: 0.47 Ohms Typical
- Low ESD clamping voltage
- Operating voltage: 3.3V
- Solid-state silicon-avalanche technology

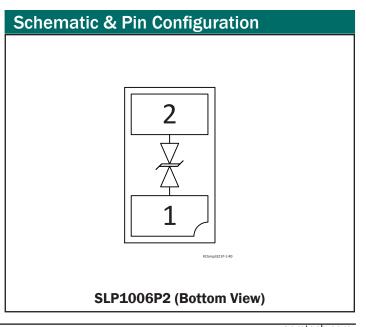
Mechanical Characteristics

- SLP1006P2 package
- Molding compound flammability rating: UL 94V-0
- Marking: Marking code
- Packaging: Tape and Reel
- Lead Finish: NiPdAu
- ◆ Pb-Free, Halogen Free, RoHS/WEEE Compliant

Applications

- ◆ USB 3.0
- ◆ HDMI 1.3/1.4
- ♦ V-By-One
- Display Port
- MHL / MDDI
- LVDS Interfaces
- eSATA Interfaces







Absolute Maximum Ratings

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20µs)	P _{PK}	25	Watts
Maximum Peak Pulse Current (tp = 8/20μs)	I _{PP}	3	Amps
ESD per IEC 61000-4-2 (Air) ¹ ESD per IEC 61000-4-2 (Contact) ¹	V _{ESD}	+/- 17 +/- 12	kV
Operating Temperature	T,	-55 to +125	°C
Storage Temperature	T _{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Reverse Stand-Off Voltage	V _{RWM}				3.3	V
Breakdown Voltage	V_{BR}	I _{BR} = 1mA	5.5	7	8.5	V
Reverse Leakage Current	I _R	V _{RWM} = 3.3V		10	50	nA
Clamping Voltage	V _c	$I_{pp} = 1A, tp = 8/20 \mu s$		9.5	10	V
Clamping Voltage	V _c	$I_{pp} = 4A, tp = 8/20\mu s$		10.5	13	V
ESD Clamping Voltage ²	V _c	$I_{pp} = 4A,$ tlp = 0.2/100ns		8.8		V
ESD Clamping Voltage ²	V _c	$I_{pp} = 16A,$ tlp = 0.2/100ns		14.5		V
Trigger Voltage ²	V _{TRIG}	tlp = 0.2/100ns		8		V
Dynamic Resistance ^{2, 3}	R _{DYN}	tlp = 0.2 / 100ns		0.47		Ω
Junction Capacitance	C _j	$V_R = OV, f = 1MHz$		0.22	0.35	pF

Notes

¹⁾ESD gun return path connected to ESD ground reference plane.

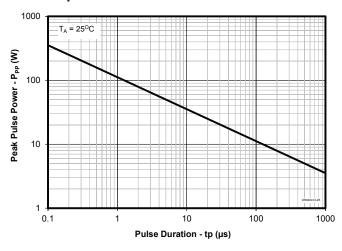
²⁾TLP Settings: $t_p = 100$ ns, $t_r = 0.2$ ns, $t_{TLP} = 0.2$ ns, $t_{$

⁴⁾ Device is electrically symmetrical

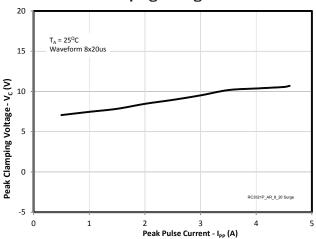


Typical Characteristics

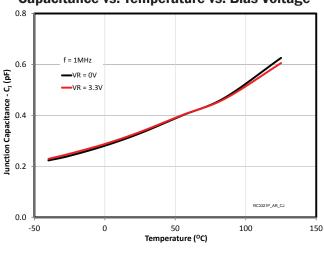
Non-Repetitive Peak Pulse Power vs. Pulse Time



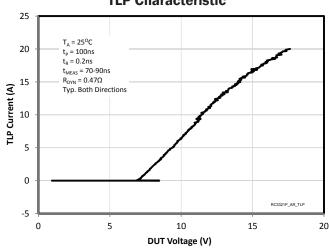
8x20us Peak Clamping Voltage vs Peak Current



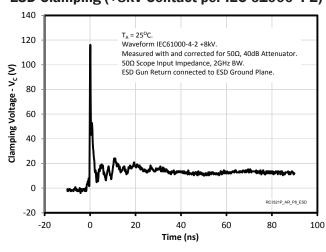
Capacitance vs. Temperature vs. Bias Voltage



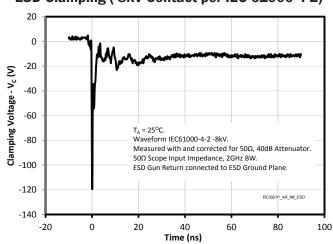
TLP Characteristic



ESD Clamping (+8kV Contact per IEC 61000-4-2)

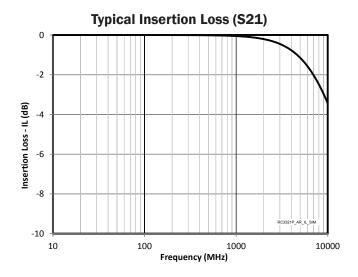


ESD Clamping (-8kV Contact per IEC 61000-4-2)





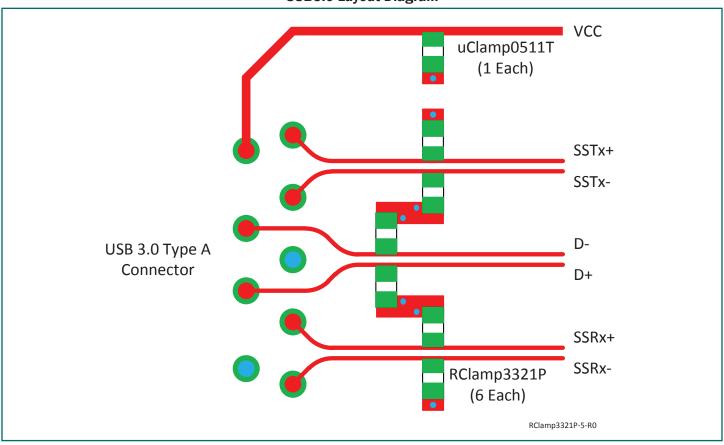
Typical Characteristics (Continued)



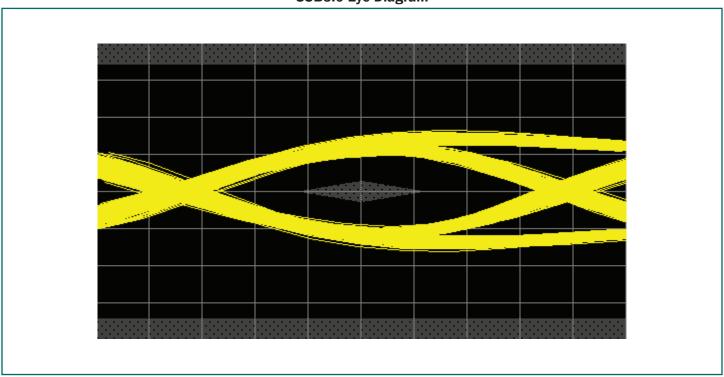


Applications Information

USB3.0 Layout Diagram



USB3.0 Eye Diagram





Applications Information

Device Connection Options

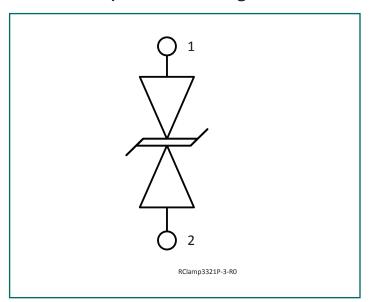
These low capacitance TVS diodes are designed to provide common mode protection for one high-speed line or differential protection for one line pair. The device is bidirectional and may be used on lines where the signal polarity is positive and negative.

Circuit Board Layout Recommendations for Suppression of ESD.

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

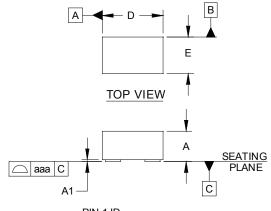
- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

Equivalent Circuit Diagram

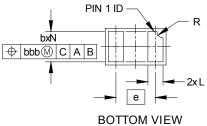




Outline Drawing - SLP1006P2



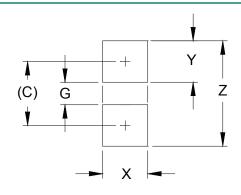
DIMENSIONS						
DIM	INCHES		MILLIMETERS			
ואווטן	MIN	NOM	MAX	MIN	NOM	MAX
Α	.016	.020	.022	0.40	0.50	0.55
A1	.000	.001	.002	0.00	0.03	0.05
b	.018	.020	.022	0.45	0.50	0.55
D	.035	.039	.043	0.90	1.00	1.10
E	.020	.024	.028	0.50	0.60	0.70
е	.0	26 BS	С	0.	65 BS0	0
L	.008	.010	.012	0.20	0.25	0.30
R	.002	.004	.006	0.05	0.10	0.15
N		2			2	
aaa	.003		0.08			
bbb	.004		0.10			



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

Land Pattern - SLP1006P2



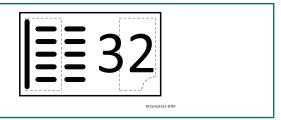
	DIMENSIONS				
DIM	INCHES	MILLIMETERS			
С	(.033)	(0.85)			
G	.012	0.30			
X	.024	0.60			
Υ	.022	0.55			
Ζ	.055	1.40			

NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.



Marking



Notes:

- 1) Device is electrically symmetrical
- 2) Marking will also include line matrix date code

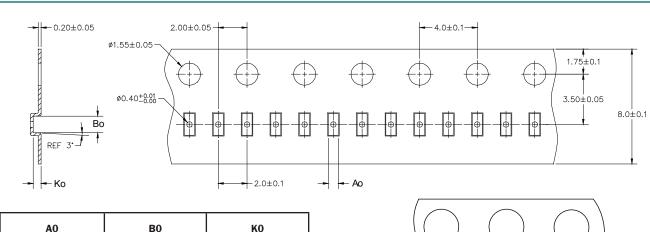
Ordering Information

Part Number	Qty per Reel	Reel Size
RClamp3321P.TNT	10,000	7 inch

Note:

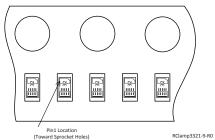
RailClamp and RClamp are trademarks of Semtech Corporation

Tape and Reel Specification



A0	В0	ко
0.69 ± 0.10 mm	1.19 ± 0.10 mm	0.66 ± 0.10 mm

Note: All dimensions in mm unless otherwise specified



Device Orientation in Tape

Contact Information

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